MIL-PRF-38535

CUSTOM MICROCIRCUIT CERTIFICATION

FOR

CLASS Q

IS HEREBY AWARDED TO

DPA COMPONENTS INTERNATIONAL

2251 Ward Avenue

Simi Valley, CA 93065

THIS CERTIFICATION IS VALID UNTIL TERMINATED BY WRITTEN NOTIFICATION FROM DSCC.
REFERENCE DSCC LETTER VQ(VQC-09-017940) FOR DETAILS PERTAINING TO THIS CERTIFICATION.

SAMUEL E. MERRITT
Director, Operations Support Directorate
Defense Supply Center, Columbus

DEFENSE LOGISTICS AGENCY
LAND AND MARITIME
POST OFFICE BOX 3990
COLUMBUS, OH 43218-3990

March 20, 2017

Douglas Young
President
DPA Components International
2251 Ward Avenue
Simi Valley, CA 93065

Dear Mr. Young:

Re: Full Class Q Level Manufacture Certification and Q and V Level Assembly and Test Certification, for MIL-PRF-38535; FSC 5962; VQC-17-031220; CN:055321.

DPA Components International has demonstrated to DLA Land and Maritime that it complies with MIL-PRF-38535, the performance specification used by the Department of Defense for monolithic integrated circuits.

This letter supersedes DSCC-VQ (VQ-09-017940) to reflect the current certification status of DPA Components International.

In addition, the parts that are manufactured using the certified technology flows are being listed on the QML-38535. This will allow DPA Components International to mark parts with "QML" or "Q". These designators have been authorized by the DoD for parts that have been produced to a QML specification (i.e., one which allows less government oversight), the use of world-wide commercial production lines, reduced finished product testing based on statistical process control (SPC), and other cost advantages.

DPA Components International is also granted Q and V Level Assembly and Test Certification for the process flows and materials used to assemble and test QML products for the quality assurance levels listed in the enclosure. This assembly and test certification listing includes subcontractors approved by DPA Components International and as documented in their Quality Management Plan.

Testing must be performed using the facilities and methods listed in the Laboratory Suitability letter VQC-17-031221, or at facilities approved by DPA Component International's Technical Review Board (TRB) using its MIL-PRF-38535 Quality Management Program Plan.

This certification is subject to the conditions in DoD 4120.24-M, Defense Standardization Program.

Any and all of the facilities mentioned on the enclosure are subject to an audit by the Qualifying Activity at any time. Offshore facilities are subject to the conditions of MIL-PRF-38535.

DPA Components International shall notify DLA Land and Maritime Qualifying Activity immediately after learning of a potential issuance of a GIDEP alert, problem advisory or major quality/reliability problem on their QML products or assembly and test processes. Failure to provide prior notification may be grounds for removal of their MIL-PRF-38535, Q and V Assembly and Test certification.

In addition, it is requested that the following activities be reported promptly to DLA Land and Maritime:

1. Changes to certified facilities, process flows, or approved testing subcontractors
2. Problem evaluation and a corrective action when:
   a. A Technology Conformance Inspection (TCI) failure has been validated
   b. The reliability of shipped parts is questionable.
3. Test optimization, including:
   a. Implementation - paragraph J.3.12, Appendix J, MIL-PRF-38535
   b. Changing, suspending or canceling a prior test optimization
4. Additions or deletions of parts in the QML-38535
5. Change of company QML contact or other key QML personnel

This certification is valid until terminated by written notice from DLA Land and Maritime, and, if warranted, it may be withdrawn by this center at any time.

If you have any questions please contact Mr. Puhalsky at (614) 692-2458.

Sincerely,

ADAMS.MICHAEL.S.1230230427

Digitally signed by ADAMS.MICHAEL.S.1230230427
Date: 2017.04.12 08:24:50 -04'00'

MICHAEL S. ADAMS
Chief
Custom Devices Branch

Visit us on the web at: https://landandmaritimeapps.dla.mil/Offices/Sourcing_and_Qualification/

Enclosure to DLA Land and Maritime-VQ (VQC-17-031220)

OPERATION	FACILITY	LOCATION	TECHNOLOGY
Wafer	Cypress Semiconductor	198 Champion Ct. San Jose, CA 95134	8" CMOS
Fabrication	Cypress Semiconductor	2401 East 86th St. Bloomington, MN 55425	C9 (90 Nanometer CMOS) R9 (90 Nanometer CMOS)
Assembly	DPACI	2251 Ward Ave. Simi Valley, CA 93065	I. Die Attach: A. Eutectic, Au-Si, Au-Sn B. Silver-Glass Adhesive C. JM7000 Silver-Cyanate Glass Adhesive II. Wire, Bonding: A. Thermosonic Gold Ball, Automatic and Manual (0.6 mil to 2.0 mil) B. Ultrasonic Aluminum Wedge, Automatic and Manual (0.6 mil to 2.0 mil) C. Large diameter Aluminum Ultrasonic Wedge Bonding (2.0 mil to 20.0 mil diameter) III. Lid Seal: A. Gold/Tin (80/20) Re-Flow, Vacuum and Belt furnaces B. Projection Cap / Lid Welding C. Seam Welding IV. Hermetically Sealed Package Types: A. Ceramic DIP w/ Metal Lid, B. Ceramic FP, QFP w/ Metal Lid. C. Ceramic PGA w/ Metal Lid. D. Ceramic CGA w/ Metal Lid. (Six Sigma) E. Ceramic LCC w/ Metal LId. F. Ceramic J-Lead w/ Metal Lid. G. Metal Can Packages w/ Metal Lid. V. Lead Forming / Trimming: A. Metal Lead Forming B. Metal Lead Trimming VI. Package Marking: A. Marking with Epoxy MIL-SPEC Ink.
	Golden Altos	402 S. Hillview Dr. Milpitas, CA 95035	Flow: GAF #1492
	Corwil Technology Corp.	1635 McCarthy Boulevard Milpitas, CA 95035-7415	Flow: Customer Specific
Test	DPACI	2251 Ward Ave. Simi Valley, CA 93065	Screening as baselined by lab suitability information letter VQC-17-031221